

**PI3DBS12212A**

**3.3V, 1-12Gbps 1-Lane 2:1 Mux/De-Mux Switch**

**Features**

- 2 Differential Channel, 2:1 Mux/DeMux
- Up to 12 Gbps for applications including USB3.0, USB3.1, 10GE, Thunderbolt, MIPI D-PHY v1.2, PCIE v3.0, SAS3.0 and SATA3.0
- Bi-directional operation
- 3dB bandwidth: 10.6GHz
- Low Bit-to-Bit Skew, 1ps typ
- Low channel-to-channel skew, 7ps typ
- Low insertion loss: -1.5dB@5 GHz, -1.7dB@6 GHz
- Return loss: -19.6dB@5 GHz, -17.2dB@6 GHz
- Low Crosstalk: -30.5dB@6 GHz
- Low Off Isolation: -17.1dB@6 GHz
- Low power consumption - 200µA typ
- Supply Voltage 3.3V
- Industrial Temperature Range: -40°C to 85°C
- ESD – 2KV Human Body Model (HBM)
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. “Green” Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](https://www.diodes.com/quality/product-definitions/) or your local Diodes representative.
- Packaging (Pb-free & Green):
  - 20-contact, TQFN(ZB20), 2.5x4.5mm
  - 18 contact, X2QFN (XUA18), 2x2mm

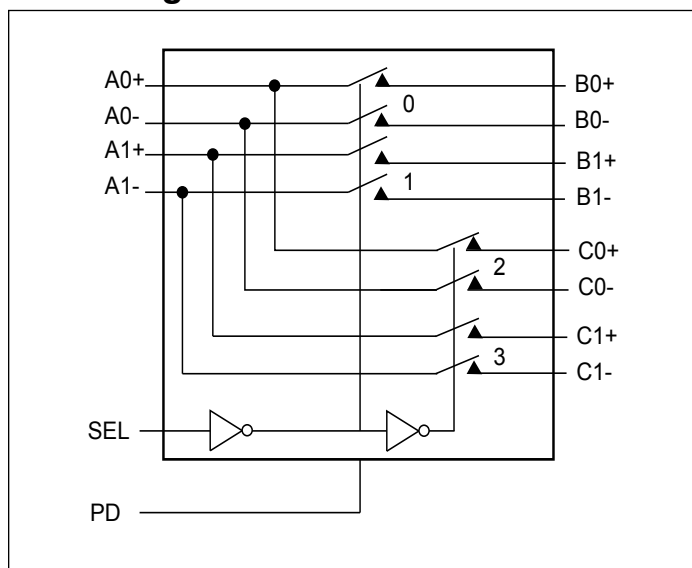
**Description**

The PI3DBS12212A is an 4 to 2 differential channel multiplexer/demultiplexer switch. This solution can switch multiple signal types up to data rate of 12Gbps. Using a unique design technique, Diodes has been able to minimize the impedance of the switch such that the attenuation observed through the switch is minimal. The unique design technique also offers a layout targeted for USB3.0, USB3.1, 10GE, Thunderbolt, MIPI D-PHY v1.2, PCIE v3.0, SAS3.0 and SATA3.0 signals, which minimizes the channel to channel skew as well as channel to channel crosstalk as required by high speed signals.

**Application**

Routing high speed differential signals such as USB3.0, USB3.1, 10GE, Thunderbolt, MIPI D-PHY v1.2, PCIE v3.0, SAS3.0 and SATA3.0.

**Block Diagram**

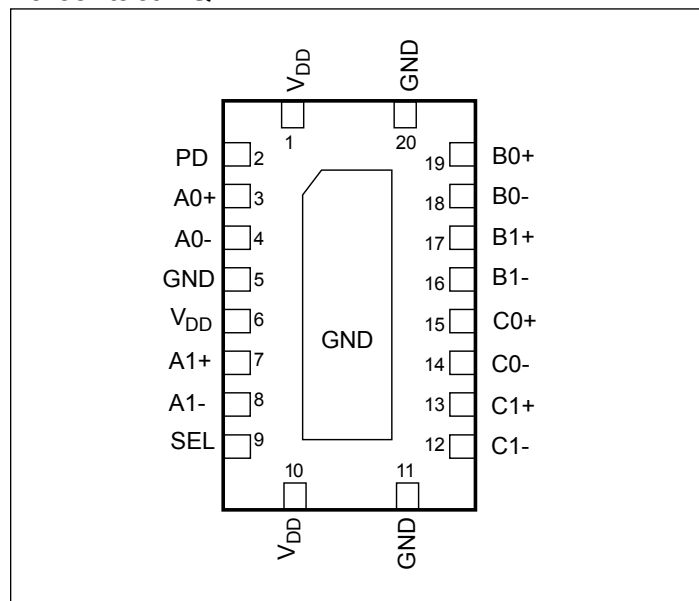


**Notes:**

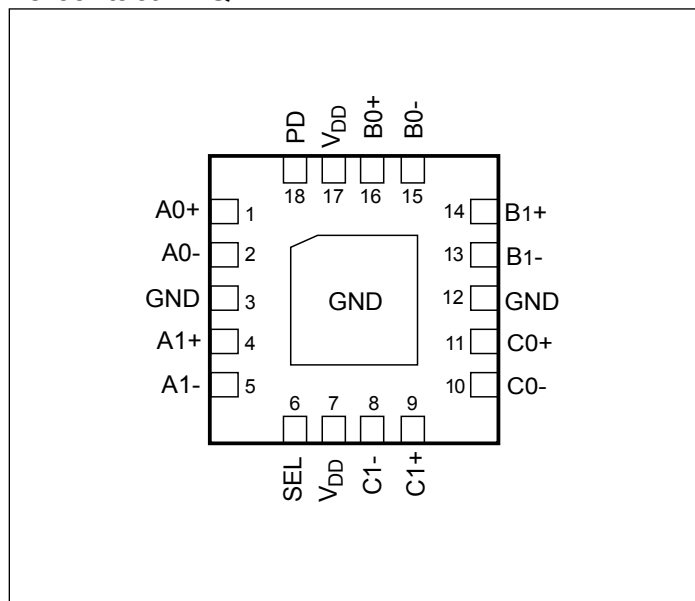
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

## Pin Configuration

### 20-contact TQFN



### 18-contact X2QFN



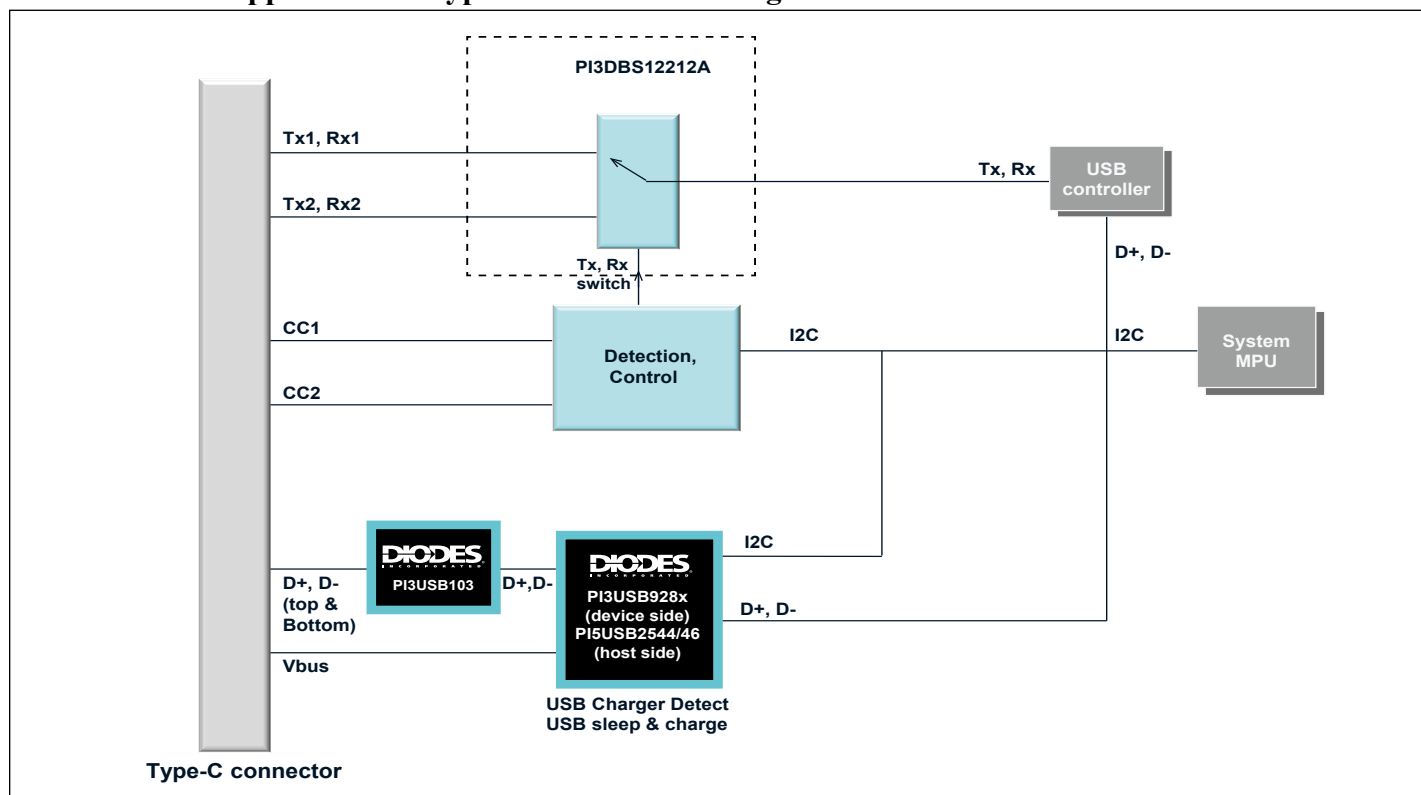
## Pin Description

20-TQFN Pin #	18-X2QFN Pin #	Pin Name	I/O	Description
3	1	A0+	I/O	Signal I/O, Channel 0, Port A
4	2	A0-		
7	4	A1+	I/O	Signal I/O, Channel 1, Port A
8	5	A1-		
19	16	B0+	I/O	Signal I/O, Channel 0, Port B
18	15	B0-		
17	14	B1+	I/O	Signal I/O, Channel 1, Port B
16	13	B1-		
15	11	C0+	I/O	Signal I/O, Channel 0, Port C
14	10	C0-		
13	9	C1+	I/O	Signal I/O, Channel 1, Port C
12	8	C1-		
9	6	SEL	I	Operation mode Select (when SEL=0: A→B, when SEL=1: A→C)
2	18	PD	I	PD = 1, Power down is enabled. Please see Truth Table.
1, 6, 10	7, 17	V <sub>DD</sub>	Pwr	3.3V ±10% Positive Supply Voltage
5, 11, 20	3, 12, Center Pad	GND	Pwr	Power ground

## Truth Table

Function	SEL	PD
$A_N$ to $B_N$	L	L
$A_N$ to $C_N$	H	L
All Switches Hi-z	x	H

## PI3DBS12212A Application in Type-C USB3.1 Switching



## Maximum Ratings

(Above which useful life may be impaired. For user guidelines, not tested.)

Storage Temperature .....	-65°C to +150°C
Junction Temperature .....	125°C
Supply Voltage to Ground Potential .....	-0.5V to +3.7V
Channel DC Input Voltage .....	-0.5V to 1.5V
DC Output Current .....	120mA
Power Dissipation .....	0.5W
Control Logic DC Input Voltage .....	-0.5V to 3.7V
ESD .....	2KV HBM

### Note:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

## Electrical Characteristics

### Recommended Operating Conditions

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V <sub>DD</sub>	3.3V Power Supply		2.85	3.3	3.6	V
I <sub>DD</sub>	Current consumption in normal operation	SEL = GND or V <sub>DD</sub> , PD = Low		0.2	1	mA
I <sub>DDQ</sub>	Current consumption when all switches are disabled	V <sub>DD</sub> = 3.3V, PD = High		6		nA
P <sub>DD</sub>	Total Power from V <sub>DD</sub> 3.3V supply	Control pins = GND or V <sub>DD</sub>		0.5		mW
P <sub>DDQ</sub>	Power consumption when all switches are disabled	V <sub>DD</sub> = 3.3V, PD = High		0.02		uW
T <sub>A</sub>	Operating temperature range		-40		85	°C

## DC Electrical Characteristics for Switching over Operating Range

Parameters	Description	Test Conditions <sup>(1)</sup>	Min.	Typ. <sup>(1)</sup>	Max.	Units
V <sub>IH</sub> - ctrl signal	Input HIGH voltage for SEL and PD	V <sub>DD</sub> =3.6V V <sub>DD</sub> =3.3V V <sub>DD</sub> =3.15V V <sub>DD</sub> =2.79V	2.0 1.85 1.7 1.7			V
V <sub>IL</sub> - ctrl signal	Input LOW voltage for SEL and PD	V <sub>DD</sub> =3.3V			0.8	V
I <sub>DDQ</sub> -ctrl	Quiescent IDD for SEL & PD	V <sub>DD</sub> =3.3V+/-10% V <sub>sel</sub> /V <sub>pd</sub> = V <sub>DD</sub>	-5		5	mA
		V <sub>DD</sub> =3.6V V <sub>sel</sub> /V <sub>pd</sub> >=2.0V			3.8	mA
		V <sub>DD</sub> =3.3V V <sub>sel</sub> /V <sub>pd</sub> >=1.85V			3.8	mA
		V <sub>DD</sub> =3.0V+/-7%(from 2.79V to 3.21V) V <sub>sel</sub> /V <sub>pd</sub> =1.8V+/-5%(from 1.7V to 1.9V)			3.8	mA
V <sub>IK</sub>	Clamp Diode Voltage	V <sub>DD</sub> = Max., I <sub>input</sub> = -18mA		-0.7	-1.2	V

## DC Electrical Characteristics for Switching over Operating Range Cont.

Parameters	Description	Test Conditions <sup>(1)</sup>	Min.	Typ. <sup>(1)</sup>	Max.	Units
I <sub>IH</sub>	Input HIGH Current for SEL and PD	V <sub>DD</sub> = Max., V <sub>input</sub> = V <sub>DD</sub>	-5		5	μA
I <sub>IL</sub>	Input LOW Current for SEL and PD	V <sub>DD</sub> = Max., V <sub>input</sub> = 0V	-5		5	
I <sub>OZH</sub>	HighZ HIGH Current, switch I/O pins	V <sub>DD</sub> = 3.3V., V <sub>input</sub> = 1.0V	-10		+10	μA
I <sub>OZL</sub>	HighZ LOW Current, switch I/O pins	V <sub>DD</sub> = Max., V <sub>input</sub> = 0V	-10		+10	μA
V <sub>P</sub>	Max voltage pass through tolerance analog switches (See Test Circuit)	V <sub>DD</sub> = 3.3V, I <sub>PASS</sub> = 10mA		1		V
V <sub>IN</sub>	Analog Signal to input of switch			1.2	1.3	V

### Note:

1. Typical values are at V<sub>DD</sub> = 3.3V, T<sub>A</sub> = 25°C ambient and maximum loading.

## Dynamic Electrical Characteristics

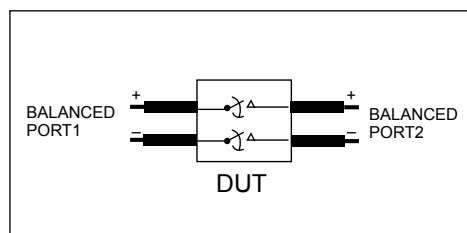
Parameter	Description	Test Conditions	Min.	Typ. <sup>(1)</sup>	Max.	Units
DDIL	Insertion Loss	f=2.5GHz f=4.0GHz f=5.0GHz f=6GHz		-0.9 -1.3 -1.5 -1.7		dB
DDRL	Differential Return Loss	f= 2.5GHz f= 4.0GHz f= 5.0GHz f= 6.0GHz		-26.4 -22.4 -19.6 -17.2		dB
DDOI	Differential OFF Isolation	f= 2.5GHz f= 4.0GHz f= 5.0GHz f= 6.0GHz		-24.9 -18.9 -17.4 -17.1		dB
DDXT	Differential Crosstalk	f= 2.5GHz f= 4.0GHz f= 5.0GHz f= 6.0GHz		-33.3 -31.9 -31.1 -30.5		dB
BW	3dB Bandwidth			10.6		GHz

### Notes:

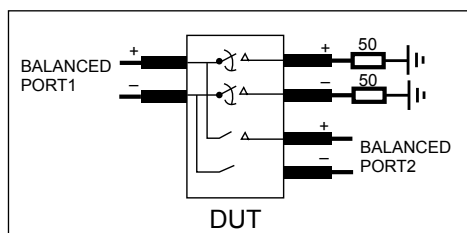
1. Guaranteed by design. Typical values are at V<sub>DD</sub> = 3.3V, T<sub>A</sub> = 25°C ambient and maximum loading.

## Switching Characteristics ( $V_{DD} = 3.0V$ to $3.6V$ )

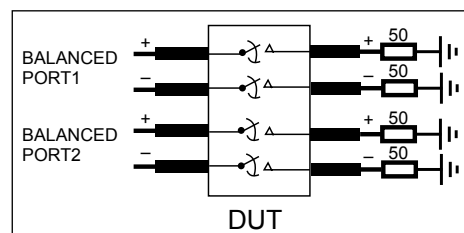
Parameters	Description	Test Conditions	Min.	Typ.	Max.	Units
tPZH, tPZL	Line Enable Time - SEL to AN, BN, CN			25	30	ns
tPHZ, tPLZ	Line Disable Time - SEL to AN, BN, CN			5	25	
tPLH	Propagation Delay, LOW to HIGH		17		36	ps
tPHL	Propagation Delay, HIGH to LOW		21		39	ps
tb-b	Bit-to-bit skew within the same differential pair			1	10	ps
tch-ch	Channel-to-channel skew				20	ps



**Diff. Insertion Loss and Return Loss  
Test Circuit**



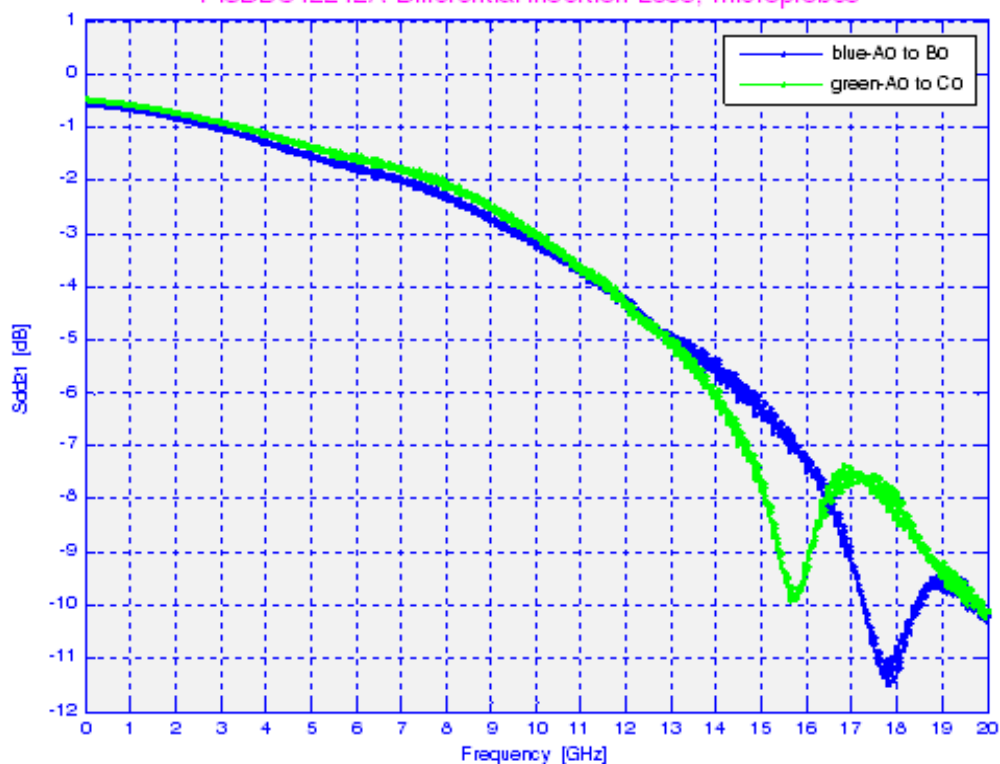
**Diff. Off Isolation Test Circuit**



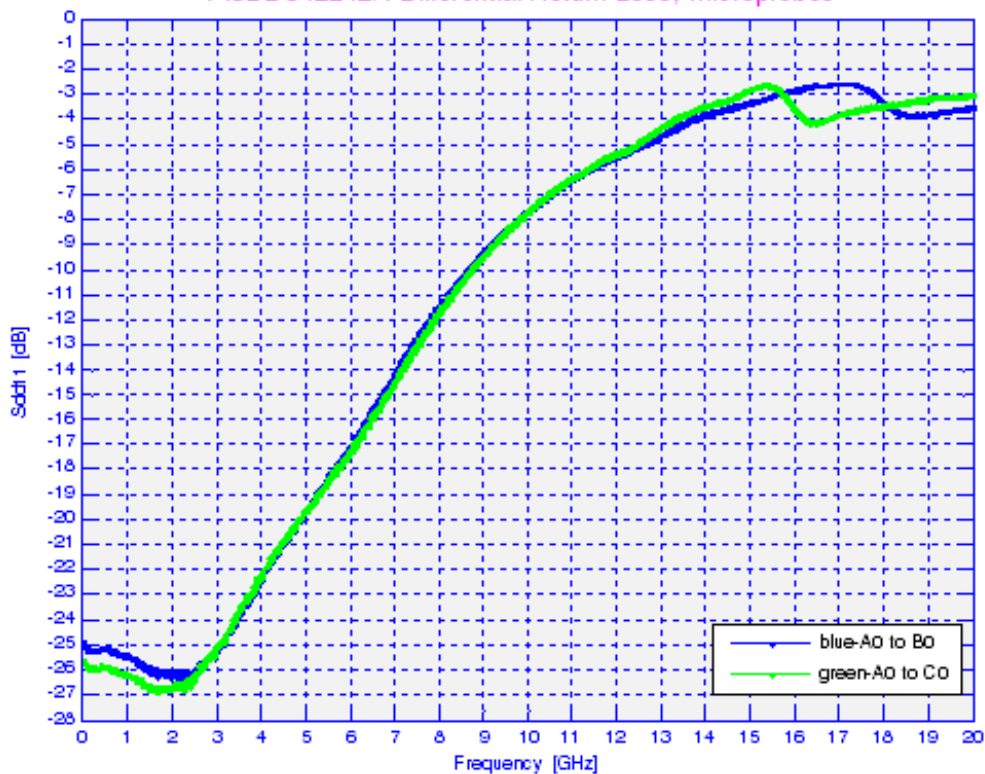
**Diff. Near End Xtalk Test Circuit**

**PI3DBS12212A**

PI3DBS12212A Differential Insertion Loss, microprobes

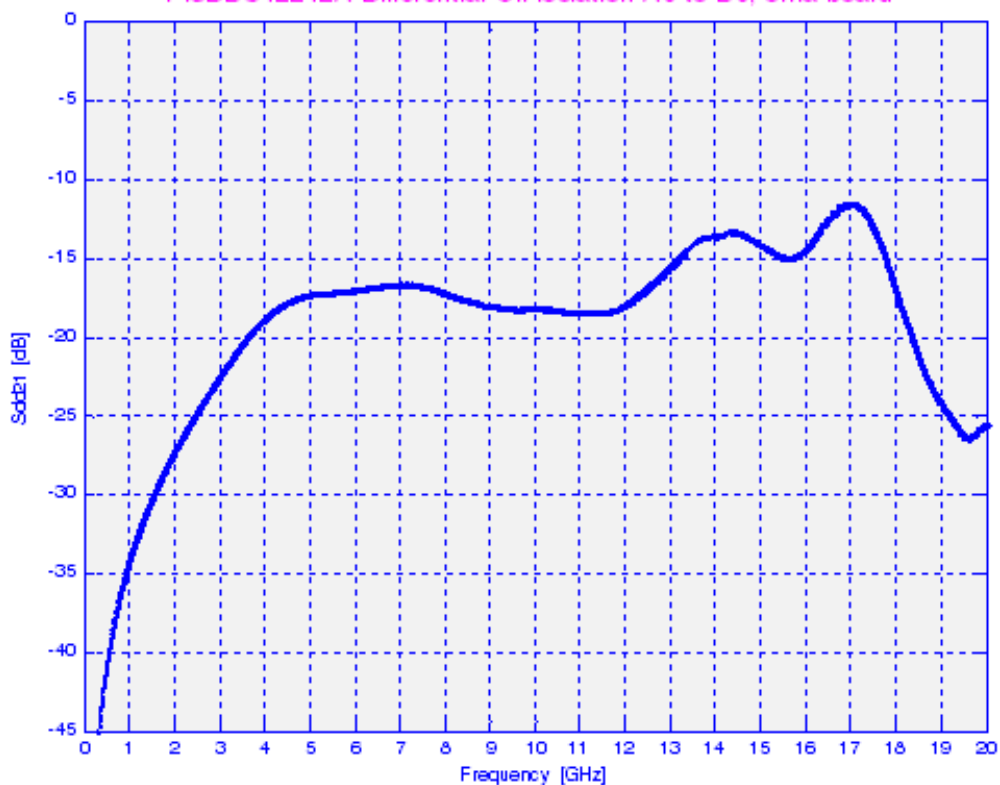


PI3DBS12212A Differential Return Loss, microprobes

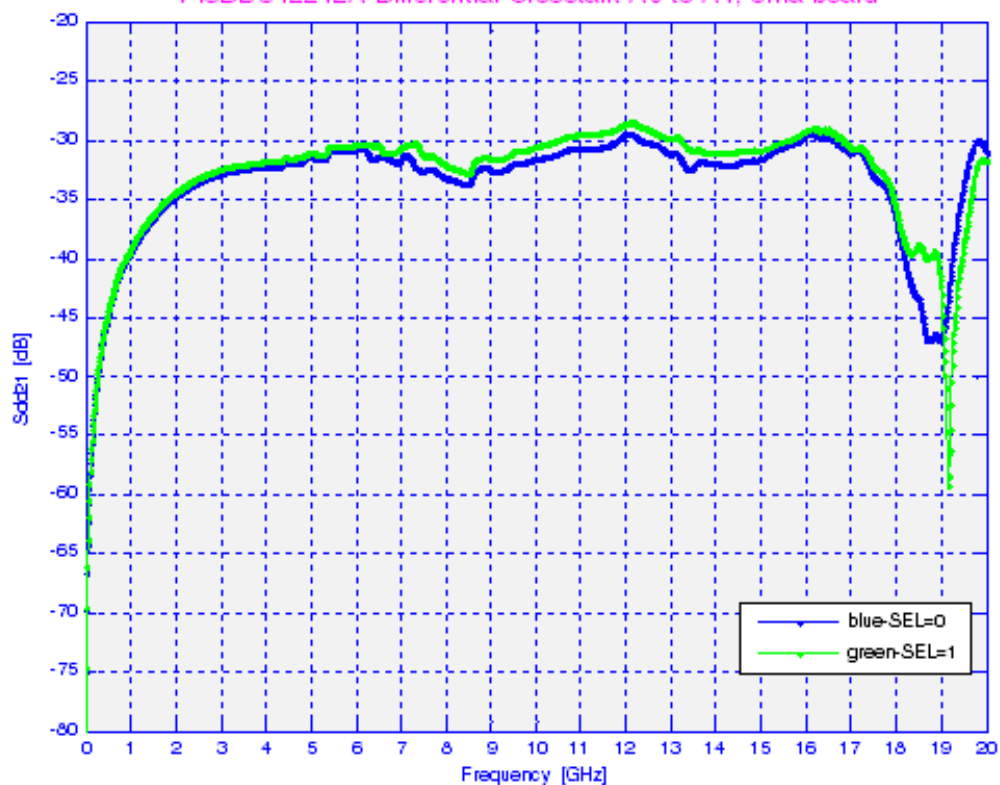


**PI3DBS12212A**

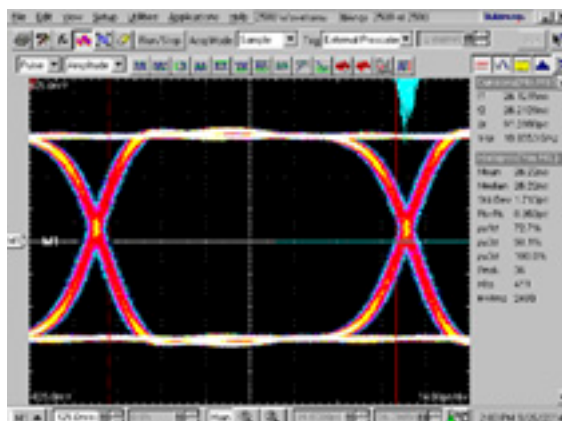
PI3DBS12212A Differential Off Isolation A0 to B0, sma board



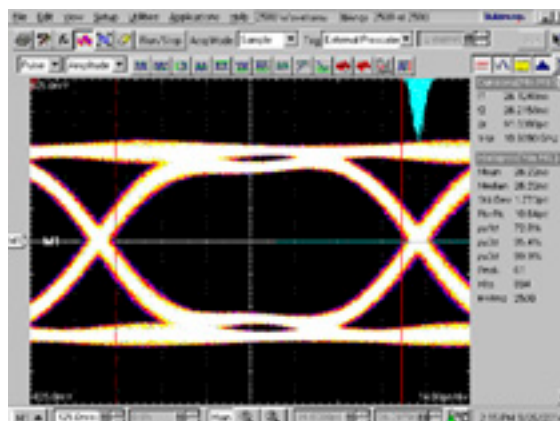
PI3DBS12212A Differential Crosstalk A0 to A1, sma board



**Before Switch**

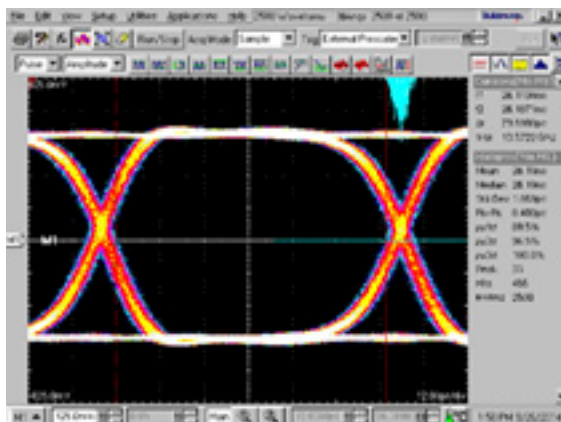


**After Switch**

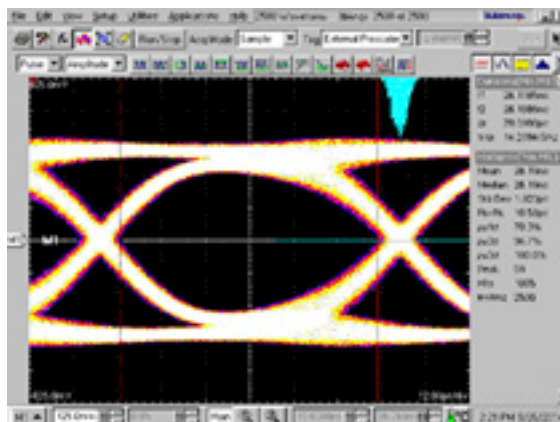


**Eye Opening at 10Gb/s using PRBS15 pattern**

**Before Switch**



**After Switch**

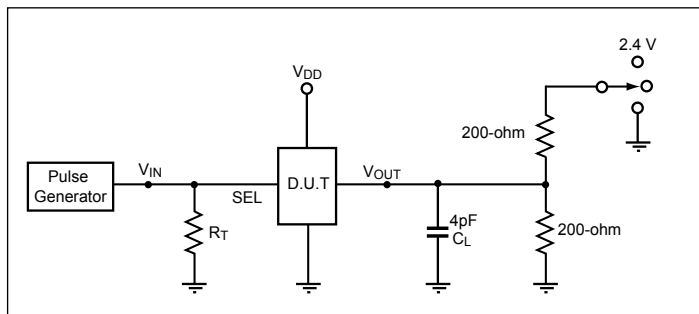


**Eye Opening at 12Gb/s using PRBS15 pattern**

## Test Circuit for Electrical Characteristics<sup>(1-5)</sup>

## Switch Positions

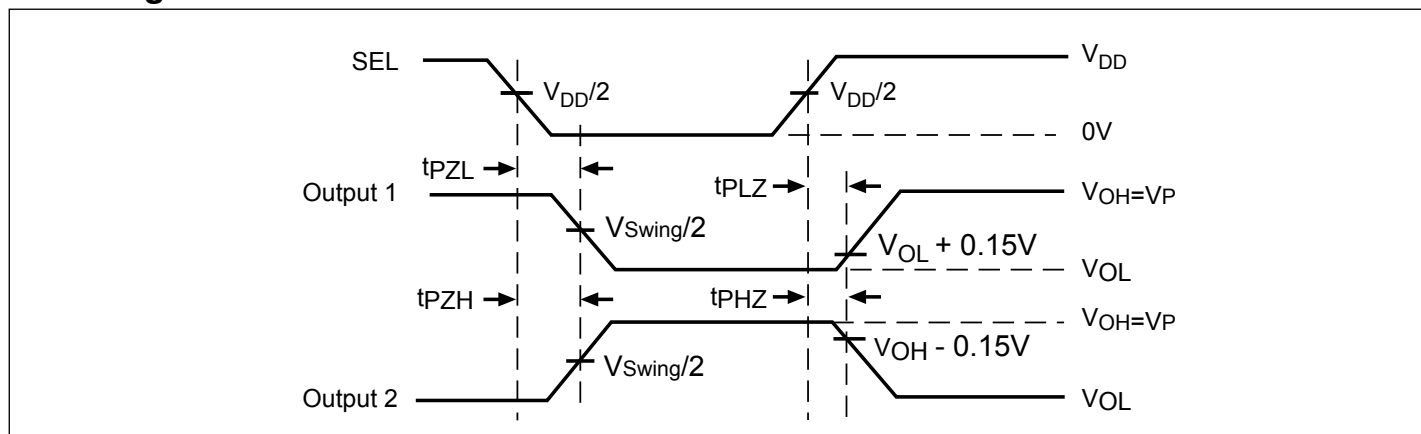
Test	Switch
$t_{PLZ}$ , $t_{PZL}$	2.4V
$t_{PHZ}$ , $t_{PZH}$	GND



### Notes:

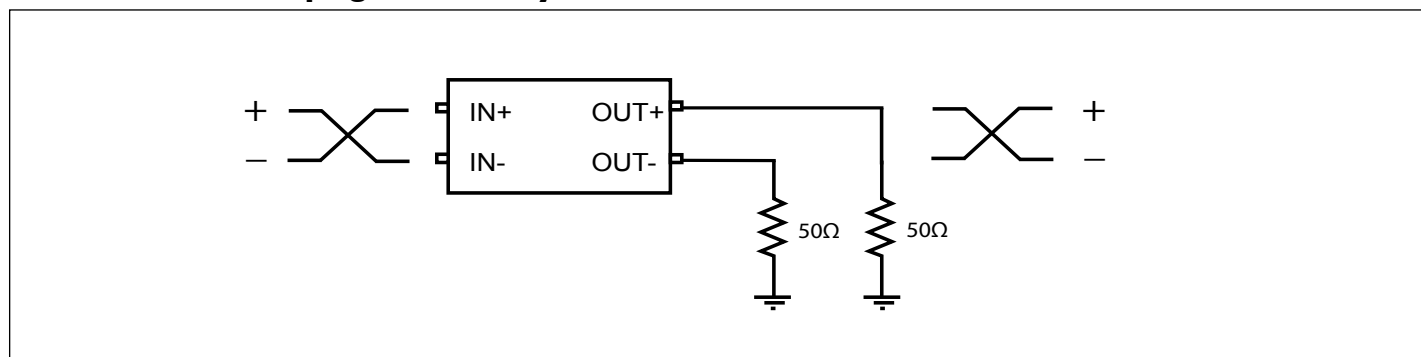
1.  $C_L$  = Load capacitance: includes jig and probe capacitance.
2.  $R_T$  = Termination resistance: should be equal to  $Z_{OUT}$  of the Pulse Generator
3. Output 1 is for an output with internal conditions such that the output is low except when disabled by the output control.  
output 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
4. All input impulses are supplied by generators having the following characteristics:  $PRR \leq \text{MHz}$ ,  $Z_O = 50\Omega$ ,  $t_R \leq 2.5\text{ns}$ ,  $t_F \leq 2.5\text{ns}$ .
5. The outputs are measured one at a time with one transition per measurement.

## Switching Waveforms

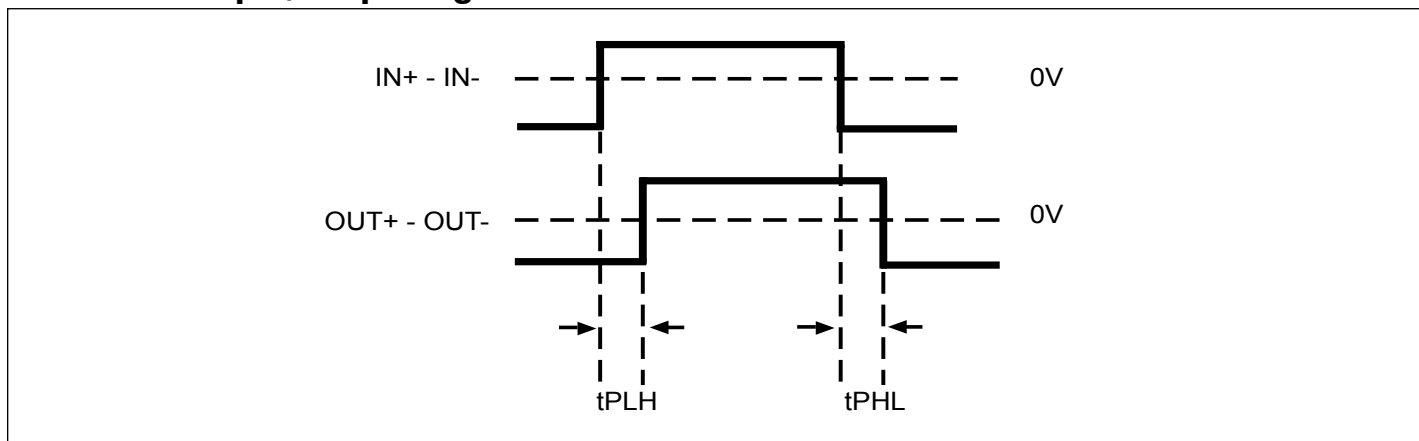


Voltage Waveforms Enable and Disable Times

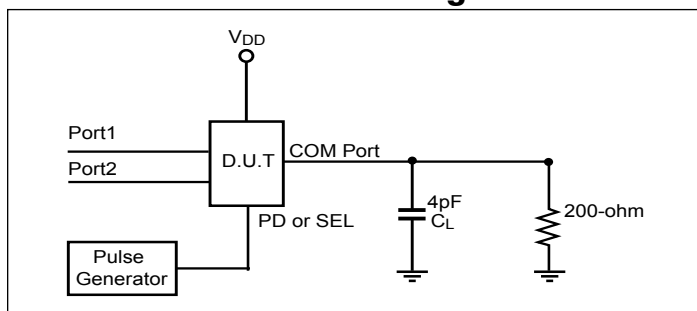
## Test Circuit for Propagation Delay



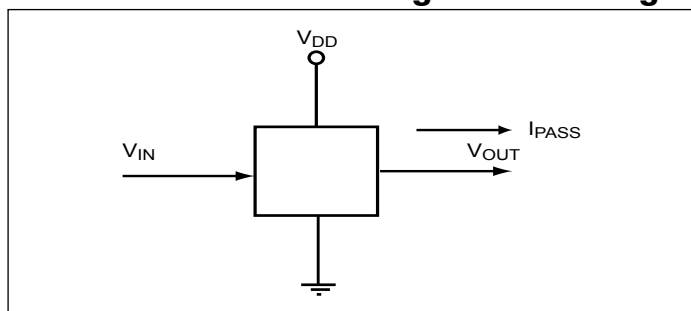
## Differential Input/Output Signal Waveform



## Test Circuit for SEL Switching Time

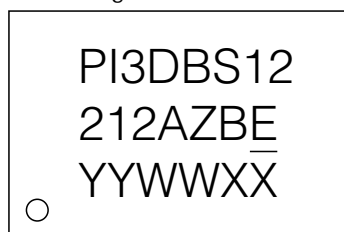


## Test Circuit for Max Voltage Pass Through



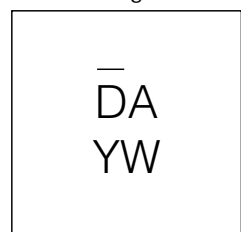
## Part Marking

ZB Package

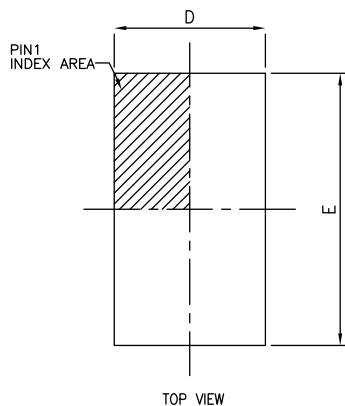


YY: Year  
WW: Workweek  
1st X: Assembly Code  
2nd X: Fab Code

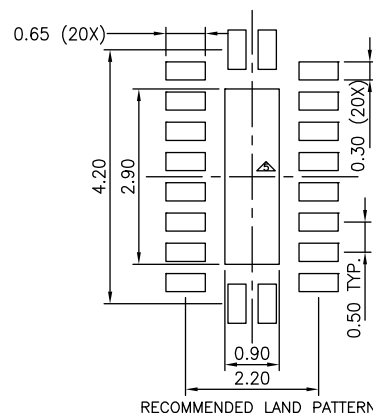
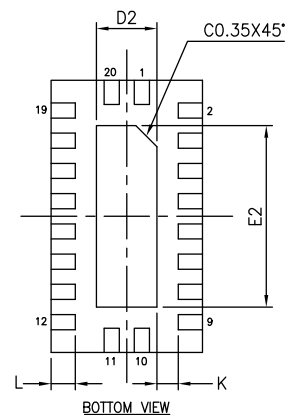
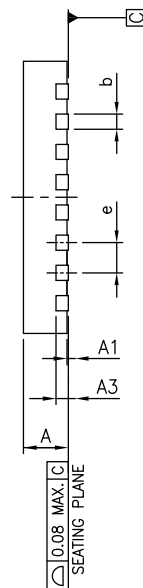
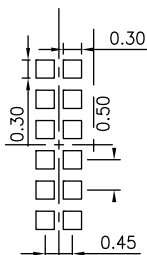
XUA Package



DA: PI3DBS12212A  
Y: Year  
W: Workweek  
Note: Date Code per MA-1251

**PI3DBS12212A**
**Packaging Mechanical: 20-TQFN (ZB)**


SYMBOLS	MIN.	NOM.	MAX.
A	--	--	1.00
A1	0.00	0.02	0.05
A3		0.20 REF.	
b	0.18	0.25	0.30
D	2.40	2.50	2.60
E	4.40	4.50	4.60
e		0.50 BSC	
L	0.30	0.40	0.50
K	0.20	--	--
D2	0.90	1.00	1.10
E2	2.90	3.00	3.10

 RECOMMENDED STENCIL DESIGN for EPAD  
 (0.125mm THICK STENCIL)


RECOMMENDED LAND PATTERN

**NOTE :**

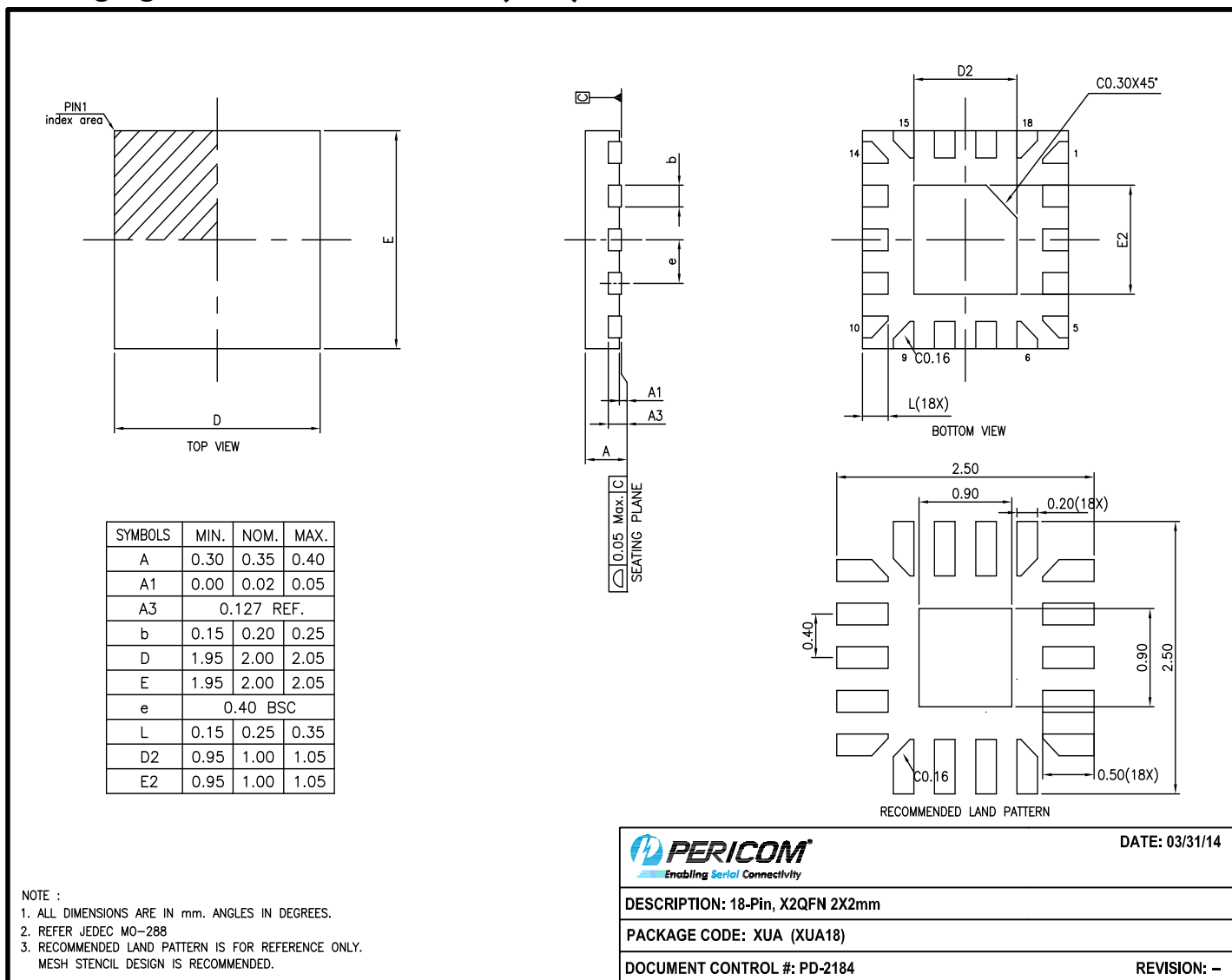
1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO-241
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA (MESH STENCIL DESIGN IS RECOMMENDED).

14-0265



DATE: 10/20/14

**DESCRIPTION: 20-Contact, Very Thin Quad Flat No-Lead (TQFN)**
**PACKAGE CODE: ZB (ZB20)**
**DOCUMENT CONTROL #: PD-2104**
**REVISION: B**

**PI3DBS12212A**
**Packaging Mechanical: 18-X2QFN (XUA)**


14-0039

**For latest package info.**

 please check: <http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/>
**Ordering Information**

Ordering Number	Package Code	Package Description
PI3DBS12212AZBEX	ZB	20-Contact, Very Thin Quad Flat No-Lead (TQFN)
PI3DBS12212AXUAEX	XUA	18-Contact, 2x2mm (X2QFN)

**Notes:**

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. E = Pb-free and Green
5. X suffix = Tape/Reel

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  2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

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